ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® MOUSTRIES® International and Pa	PC. Bannockl	burn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration entities the declaration entities and the declaration entities and the declaration entities and the declaration entities are an entities are an entities and the declaration entities are an entits are an entities are an entits are an entities are an entities	on of the su	bstances v all lower	vithin the manufactu level materials for v	urer listed which the	item. Note: nanufacture	if the item is an as er has engineering	sembly with low responsibility.	
				Form Type Distribute	e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia				rials and N	als and Mfg Information				
upplier Information														
Company name* Con		Company un	Company unique ID			Unique ID Authority				Respon	Response Date*			
nsemi										2025-0	2025-07-16			
ontact Name Title - Contact			ct	P			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Env			Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Representative			resentative			Phone - Representative*				Email ·	Email - Representative*			
Product-Env-Stewards Product			oduct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	ate Version Manufacturing Sit		Ianufacturing Site		Weight*	UOM	Unit Type	
	MBRA1	MBRA130LT3G REC SMA 1A		30V SHTKY TR		2025-07-16		C	CNP		62.27	mg	Each	
Ianufacturing Proccess Informa	tion							·						
Terminal Plating / Grid Array M	aterial	Ferminal Base	Alloy	J-STD-020 MSL Rating		Peak Proce	Peak Process Body Temperat		ure Max Time at Peak Te		ture Num	ber of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU All		CU Alloy	1			<b>260</b> C		С	30	seco	nds 3			
omments														
vel 1 - maximum time at peak temperat	ure during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not ndependently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of hat agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provid										
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	6.0	mg	Supplier	Iron (Fe)	7439-89-6		0.006	mg
			Supplier	Copper (Cu)	7440-50-8		5.9922	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0018	mg
Die	1.12	mg	Supplier	Silicon (Si)	7440-21-3		1.12	mg
Die Attach Solder	2.92	mg	Supplier	Silver (Ag)	7440-22-4		0.073	mg
			А	Lead (Pb)	7439-92-1	7a	2.701	mg
			Supplier	Tin (Sn)	7440-31-5		0.146	mg
Lead Frame	22.63	mg	Supplier	Iron (Fe)	7439-89-6		0.0226	mg
			Supplier	Copper (Cu)	7440-50-8		22.6006	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0068	mg
Mold Compound-Black	29.52	mg	Supplier	Polycondensate of 4,4'- bis(methoxymethyl)biphenyl and phenol	205830-20-2		0.738	mg
			Supplier	Triphenylphosphine	603-35-0		0.1476	mg
			Supplier	Trimethoxysilylpropanethiol	4420-74-0		0.1476	mg
			Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'- tetramethylbiphenyl	85954-11-6		0.1476	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2952	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		26.568	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.476	mg
Plating	0.08	mg	Supplier	Tin (Sn)	7440-31-5		0.08	mg